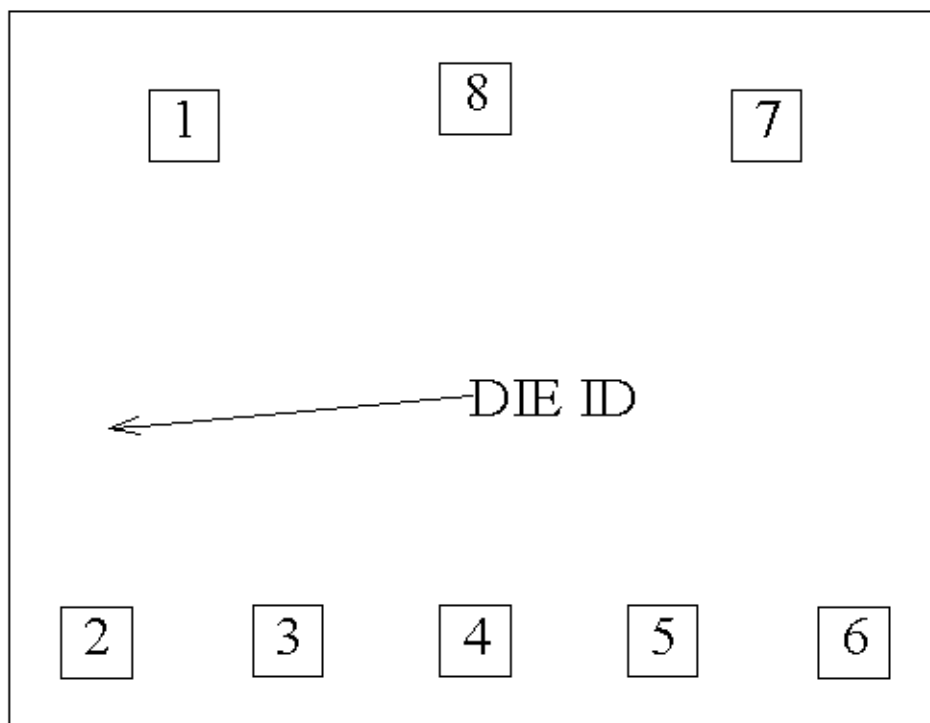


LM2904 MDC MWC
LOW POWER DUAL OPERATIONAL AMPLIFIER

February 13, 2002

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|-----------------------------------|-----------------------------|-------------|
| Physical Die Identification | LM158D | Bond Pad Opening Size (min) | 92µm x 92µm |
| Die Step | D | Bond Pad Metalization | ALUMINUM |
| Physical Attributes | | Passivation | VOM NITRIDE |
| Wafer Diameter | 150mm | Back Side Metal | Bare Back |
| Die Size (Drawn) | 1219µm x 940µm 48mils x 37mils | Back Side Connection | Floating |
| Thickness | 330µm Nominal | | |
| Min Pitch | 244µm Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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| Die Bond Pad Coordinate Locations (D -Step) | | | | | | |
|---|--------|-----------------|------|----------|---|----|
| (Referenced to die center, coordinates in μm) NC = No Connection | | | | | | |
| SIGNAL | PAD# | X/Y CORRDINATES | | PAD SIZE | | |
| NAME | NUMBER | X | Y | X | Y | |
| OUTPUT A | 1 | -381 | 320 | 92 | x | 92 |
| INPUT A - | 2 | -496 | -357 | 92 | x | 92 |
| INPUT A + | 3 | -245 | -355 | 92 | x | 92 |
| GND | 4 | 0 | -355 | 92 | x | 92 |
| INPUT B + | 5 | 245 | -355 | 92 | x | 92 |
| INPUT B - | 6 | 496 | -357 | 92 | x | 92 |
| OUTPUT B | 7 | 381 | 320 | 92 | x | 92 |
| V+ | 8 | 0 | 355 | 92 | x | 92 |

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IN U.S.A.

Tel: 1 877 Dial Die (1 877 342 5343)
Fax: 1 207 541 6140

IN EUROPE

Tel: 49 (0) 8141 351492 / 1495
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Tel: (852) 27371701

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